ULTRA MINIATURE 2-POLES 2A (SLIM PROFILE SIGNAL RELAY)

FTR-B4 Series

RoHS compliant

■ FEATURES

- DPDT 2C
- Ultra miniature slim type relay for surface mounting

Height: 9.3 mm maximum (THT)

10 mm maximum (SMT)

Weight: Approximately 1.0 g

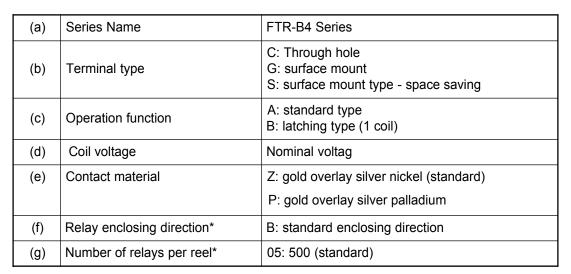
- Conforms to Bellcore & FCC part 68, and Telcordia & FCC part 68
- Conforms to UL1950 / CSA 950, IEC 950 / EN60950 spacing and high breakdown voltage

Clearance: 1.0mm Creepage: 1.6mm

Basic insulation, 150V working voltage, pollution degree 2

- · High reliable birfuracted gold overlay silver contact
- Low power consumption 140 mW (standard), 100 mW (latching)
- RoHS compliant since date code: 0430B8
 Please see page 8 for more information

ORDERING INFORMATION

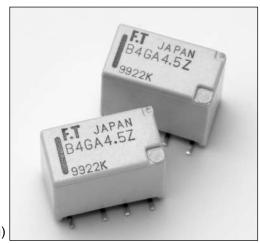


Remarks: Actual marking on relay would not carry code FTR and be as below: Ordering code Actual marking

Notes: *FTR-B4CA4.5Z → B4CA4.5Z

- Only surface mount types (G and S) are applicable
- All relays are packaged in tubes unles P/N ends with -B05





■ PART NUMBERS

Ordering Part Number	Series	Terminal Type	Operation	Coil Voltage	Contact Material
FTR-B4CA1.5Z		C: through hole		1.5	
FTR-B4CA003Z				3	
FTR-B4CA4.5Z				4.5	
FTR-B4CA006Z				6	
FTR-B4CA009Z				9	
FTR-B4CA012Z				12	
FTR-B4CA024Z				24	
FTR-B4GA1.5Z				1.5	
FTR-B4GA003Z		G: surface mount	A: mono-stable (standard type)	3	
FTR-B4GA4.5Z	FTR-B4			4.5	7. A. A. A. N.
FTR-B4GA006Z				6	Z: Au-Ag-Ni P: Au-Ag-Pd
FTR-B4GA009Z				9	
FTR-B4GA012Z				12	
FTR-B4GA024Z				24	
FTR-B4SA1.5Z		S: space sav- ing surface mount		1.5	
FTR-B4SA003Z				3	
FTR-B4SA4.5Z				4.5	
FTR-B4SA006Z				6	
FTR-B4SA009Z				9	
FTR-B4SA012Z				12	
FTR-B4SA024Z				24	

Latching type (1 coil)

Ordering Part Number	Series	Terminal Type	Operation	Coil Voltage	Contact Material
FTR-B4CB1.5Z	-	C: through hole		1.5	
FTR-B4CB003Z				3	
FTR-B4CB4.5Z				4.5	
FTR-B4CB006Z				6	
FTR-B4CB009Z		11010		9	
FTR-B4CB012Z				12	
FTR-B4CB024Z				24	
FTR-B4GB1.5Z				1.5	
FTR-B4GB003Z				3	Z: Au-Ag-Ni P: Au-Ag-Pd
FTR-B4GB4.5Z				4.5	
FTR-B4GB006Z	FTR-B4	G: surface mount	B: latching	6	
FTR-B4GB009Z		mount		9	1.7.47.914
FTR-B4GB012Z				12	
FTR-B4GB024Z				24	
FTR-B4SB1.5Z	-	S: space sav- ing surface mount		1.5	
FTR-B4SB003Z				3	
FTR-B4SB4.5Z				4.5	
FTR-B4SB006Z				6	
FTR-B4SB009Z				9	
FTR-B4SB012Z				12	
FTR-B4SB024Z				24	

■ COIL DATA CHART

Coil Voltage	Nominal Voltage (VDC)	Max. Coil Voltage*	Coil Resistance (±10%)	Must Operate Voltage*2	Must Release Voltage* ²	Nominal Power (mW)
1.5	1.5	3.53 VDC	16.1 Ω	1.13 VDC	0.15 VDC	
003	3	7.05 VDC	64.3 Ω	2.25 VDC	0.3 VDC	
4.5	4.5	10.58 VDC	145 Ω	3.38 VDC	0.45 VDC	140
006	6	14.10 VDC	257 Ω	4.5 VDC	0.6 VDC	140
009	9	21.15 VDC	579 Ω	6.75 VDC	0.9 VDC	
012	12	28.20 VDC	1,028 Ω	9.0 VDC	1.2 VDC	
024	24	56.40 VDC	2,504 Ω	18.0 VDC	2.4 VDC	230

^{*1:} No contact current at 20°C. Please see 'operating range' data for other conditions. *2: Specified values are subject to pulse wave voltage.

Latching type (1 coil)

Coil Voltage	Nominal Voltage (VDC)	Max. Coil Voltage* 1	Coil Resistance (±10%)	Must Operate Voltage* ²	Must Release Voltage* ²	Set/Re-set current	Nominal Power (mW)
1.5	1.5	3.53 VDC	22.5 Ω	1.13 VDC	-0.13 VDC	50mA	
003	3	7.05 VDC	90 Ω	2.25 VDC	-2.25 VDC	25mA	
4.5	4.5	10.58 VDC	203 Ω	3.38 VDC	-3.38 VDC	17mA	100
006	6	14.10 VDC	360 Ω	4.5 VDC	-4.5 VDC	13mA	100
009	9	21.15 VDC	810 Ω	6.75 VDC	-6.75 VDC	8mA	
012	12	28.20 VDC	1,440 Ω	9.0 VDC	-9.0 VDC	6mA	
024	24	56.40 VDC	4,800 Ω	18.0 VDC	-18.0 VDC	4mA	120

Note: All values in the table are measured at 20°C.

■ SPECIFICATIONS

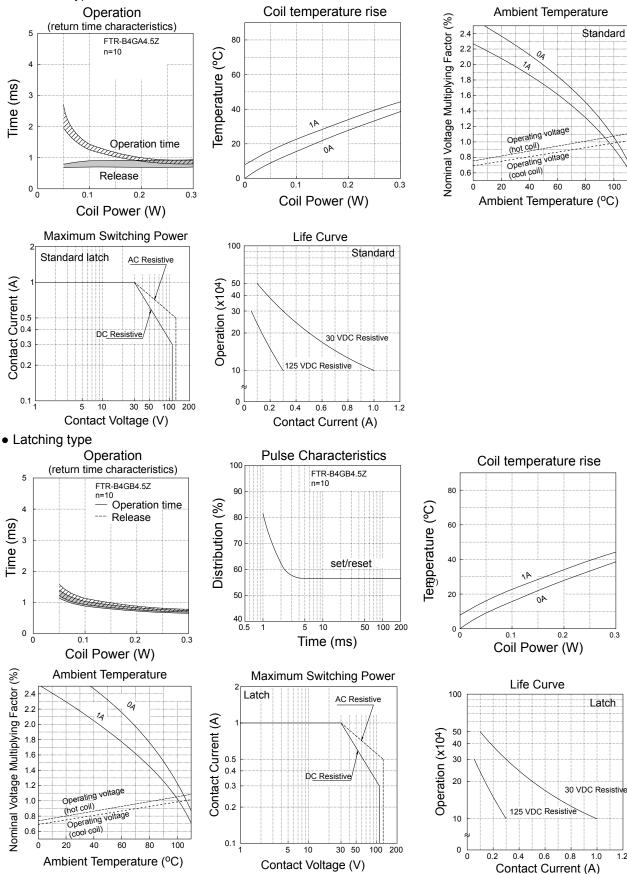
			Standard Type	Latching Type		
			FTR-B4()A	FTR-B4 () B		
Contact	Arrangement		2 Form C			
	Contact material		Gold overlay silver nickel / Gold overlay silver palladium			
	Contact type		Bifurcated contact (cross-bar)			
	Contact resistance (ini	tial value)	100mΩ maximum at 6VDC 1			
	Contact rating		30 VDC 1A, 125 VAC 0.3 A (resistive)			
	Maximum carrying cur	rent	2A			
	Maximum switching po	ower	62.5 VA / 30W			
	Maximum switching vo	ltage	250 VAC/ 220 VDC			
	Minimum switching load*		10m VDC, 0.01mA*			
Coil	Nominal power (at 20°	C)	140 mW up to 230 mW	100 mW up to 130 mW		
	Operate power (at 20°	C)	80 mW up to 130 mW	57 mW up to 68 mW		
	Operating temperature	e (no frost)	-40°C to +85°C			
Time value	Operate (at nominal vo	oltage, without bounce)	3ms maximum	3ms maximum (set)		
	Release (at nominal vo	oltage, without bounce)	3ms maximum	3ms maximum (reset)		
Life	Mechanical		50 x 10 ⁶ operations	20 x 10 ⁶ operations		
	Electrical (resistive load)	DC load	100 x 10 ³ ops. min. at 1A, 30 VDC (at 0.5 Hz)			
		AC load	100 x 10 ³ ops. min. at 0.3A, 125VAC (at 0.5 Hz)			
Vibration	Misoperation		10 to 55 Hz at double amplitude of 3 mm			
resistance	Endurance		10 to 55 Hz at double amplitude of 5 mm			
Shock	Misoperation		Min. 750 m/s ²			
resistance	Endurance		Min. 1,000 m/s ²			
Weight			Approximately 1.0 g			
US/CSA	Contact rating		0.5A, 125 VAC; 1A, 30 VDC; 0.3A, 110 VDC			

^{*1} Minimum switching loads mentioned above are reference values. Please perform the confirmation test with the actual load before production since reference values may vary according to switching frequencies, envionmental conditions and expected reliability levels.

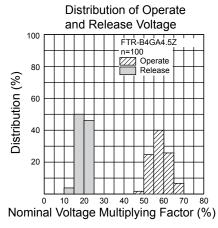
^{*1:} No contact current at 20°C. Please see 'operating range' data for other conditions.

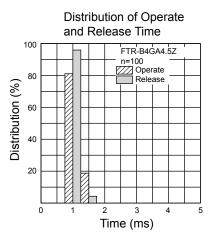
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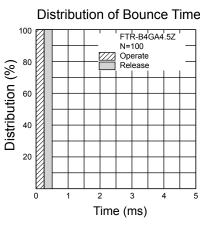
■ CHARACTERISTIC DATA

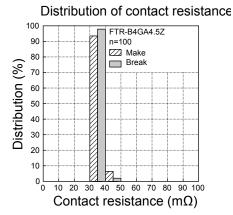


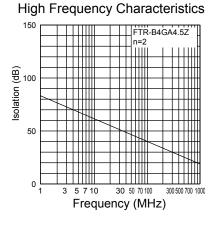
■ REFERENCE DATA

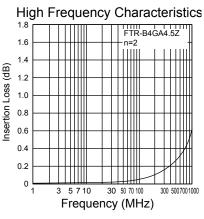


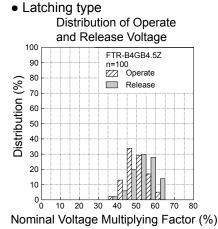


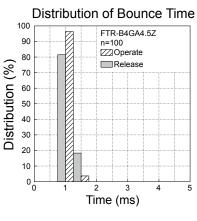


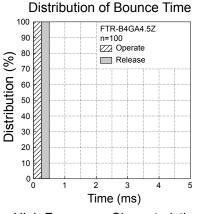


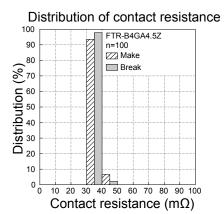


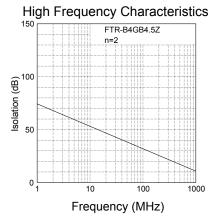


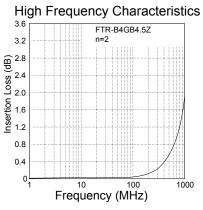




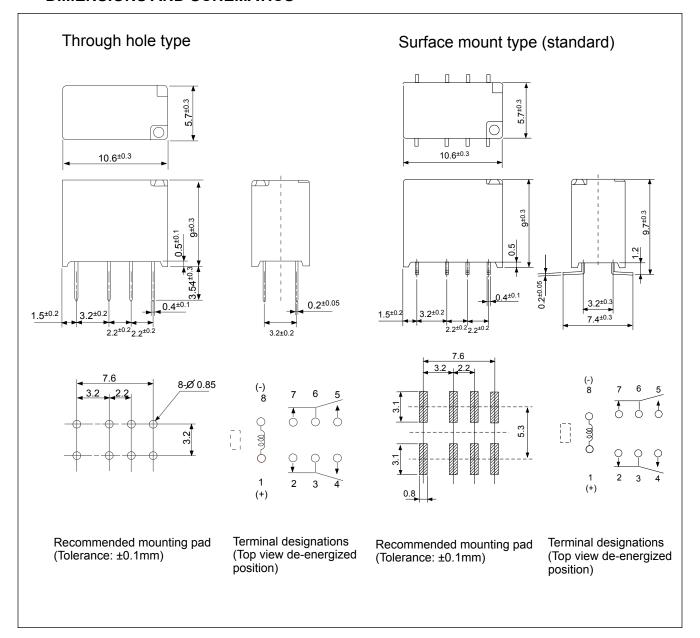




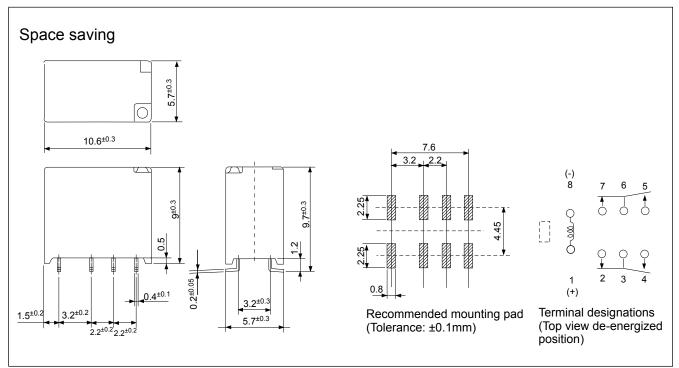




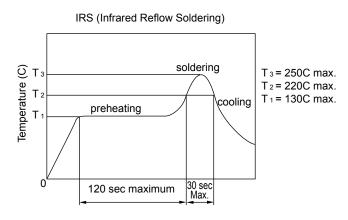
■ DIMENSIONS AND SCHEMATICS



■ DIMENSIONS AND SCHEMATICS



■ RECOMMENDED SOLDERING CONDITIONS FOR SMT (TEMPERATURE PROFILE)



Note:

- 1.Temperature profiles show the tempera ture of PC board surface.
- Please perform soldering test with your actual PC board before mass produc tion, since the temperatures of PC board surfaces vary according to the size of PC board, status of parts mount ing and heating method.

■ PRECAUTIONS

- For details on general precautions, refer to the section on technical descriptions.
- Since this is a polarized relay, follow the instructions of the internal wiring diagram for the +/- connections of the coil.
- Note that the terminal layout and internal wiring of the surface mount relay are a top view.
- SMT versions of the FTR-B4 relays have moisture sensitivity level 3, acc. JEDEC-J-STD-020D
- SMT versions of the FTR-B4 relays will be shipped in "Dry Pack". Relays have an "Out of Bag" storage time of 192h.

RoHS Compliance and Lead Free Relay Information

1. General Information

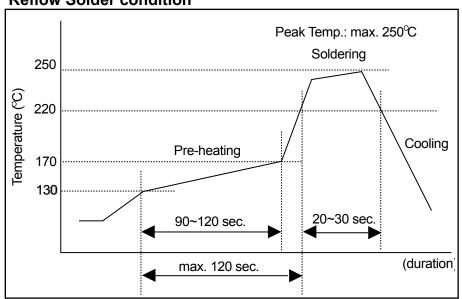
- If applicable, relays produced after the specific date code that is indicated on each data sheet are lead-free
 now. All of our signal and power relays are lead-free. Please refer to Lead-Free Status Info.
 (http://www.fujitsu.com/us/downloads/MICRO/fcai/relays/lead-free-letter.pdf)
- Lead free solder plating currently used in relays is Sn-3.0Ag-0.5Cu. From February 2005 forward Sn-3.0Cu-Ni will be used for the FTR-B3 and FTR-B4 series relays.
- All signal and power relays also comply with RoHS. Please refer to individual data sheets. Relays that are RoHS compliant do not contain the 5 hazardous materials that are restricted by RoHS directive (lead, mercury, chromium IV, PBB, PBDE, decaBDE and PFOS).
- It has been verified that using lead-free relays in leaded assembly process will not cause any problems (compatible).
- "LF" is marked on each outer and inner carton. (No marking on individual relays).
- To avoid lead containing relays (for lead-free sample, etc.) please consult with area sales office.
- We will shiplead containing relays as long as the lead containing relay inventory exists.

 Note: Cadmium was exempted from RoHS on October 21, 2005. (Amendment to Directive 2002/95/EC)

2. Recommended Lead Free Solder Profile

 Recommended solder paste Sn-3.0Ag-0.5Cu or Sn-3.0 Cu-Ni (only FTR-B3 and FTR-B4 from February 2005.

Reflow Solder condition



Flow Solder condition:

Pre-heating: maximum 120°C dip within 5 sec. at 260°C solder bath

Solder by Soldering Iron:

Soldering Iron

Temperature: maximum 360°C Duration: maximum 3 sec.

We highly recommend that you confirm your actual solder conditions

3. Moisture Sensitivity

• Moisture Sensitivity Level is not applicable to electromechanical relays.

4. Tin Whisker

 SnAgCu and SnCuNi solder are known as low risk of tin whisker. No considerable whisker length was found by our in-house test.

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